

Electronic Patent Application Fee Transmittal

Application Number:	10581928			
Filing Date:	07-Jun-2006			
Title of Invention:	THERMOSETTING RESIN COMPOSITION, RESIN SHEET AND RESIN SHEET FOR INSULATED SUBSTRATE			
First Named Inventor/Applicant Name:	Koichi Shibayama			
Filer:	Lee Cheng/Conlee Tercenio			
Attorney Docket Number:	MIY-0212			
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U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	3	3	9
Total in USD (\$)				1819